(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
6 March 2003 (06.03.2003)

PCT

(10) International Publication Number
WO 03/019656 A3

(51) International Patent Classification[7]: H01L 23/50, 23/64, H05K 1/16

(21) International Application Number: PCT/US02/26756

(22) International Filing Date: 22 August 2002 (22.08.2002)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/314,905 24 August 2001 (24.08.2001) US

(71) Applicant: 3M INNOVATIVE PROPERTIES COMPANY [US/US]; 3M Center, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

(72) Inventors: SYLVESTER, Mark, F.; Post Office Box 33427, Saint Paul, MN 55133-3427 (US). HANSON, David, A.; Post Office Box 33427, Saint Paul, MN 55133-3427 (US). PETEFISH, William, G.; Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

(74) Agents: FONSECA, Darla, P. et al.; Office of Intellectual Property Counsel, Post Office Box 33427, Saint Paul, MN 55133-3427 (US).

(81) Designated States *(national)*: AE, AG, AL, AM, AT (utility model), AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ (utility model), CZ, DE (utility model), DE, DK (utility model), DK, DM, DZ, EC, EE (utility model), EE, ES, FI (utility model), FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NO, NZ, OM, PH, PL, PT, RO, RU, SD, SE, SG, SI, SK (utility model), SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

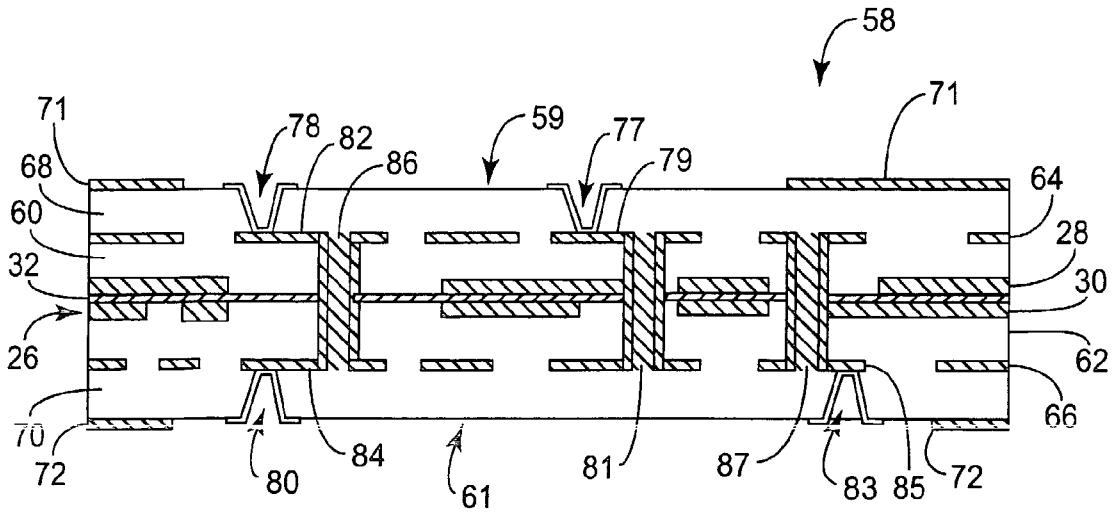
Declarations under Rule 4.17:
— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii)) for all designations*
— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for all designations*

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
20 November 2003

[Continued on next page]

(54) Title: INTERCONNECT MODULE WITH REDUCED POWER DISTRIBUTION IMPEDANCE



(57) Abstract: An interconnect module for an integrated circuit chip incorporates a thin, high dielectric constant embedded capacitor structure to provide reduced power distribution impedance, and thereby promote higher frequency operation. The interconnect module is capable of reliably attaching an integrated circuit chip to a printed wiring board via solder ball connections, while providing reduced power distribution impedance of less than or equal to approximately 0.60 ohms at operating frequencies in excess of 1.0 gigahertz.

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